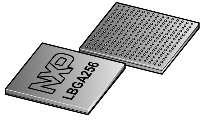

SOT740-4

LBGA256, plastic, low profile ball grid array; 256 balls; 1 mm pitch; 17 mm x 17 mm x 1.16 mm body

11 September 2018 | Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LBGA256
Package style descriptive code	LBGA (low profile ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-02-2016
Manufacturer package code	98ARH98219A

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
package height	-	1.16	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	256	-	

2 Package outline

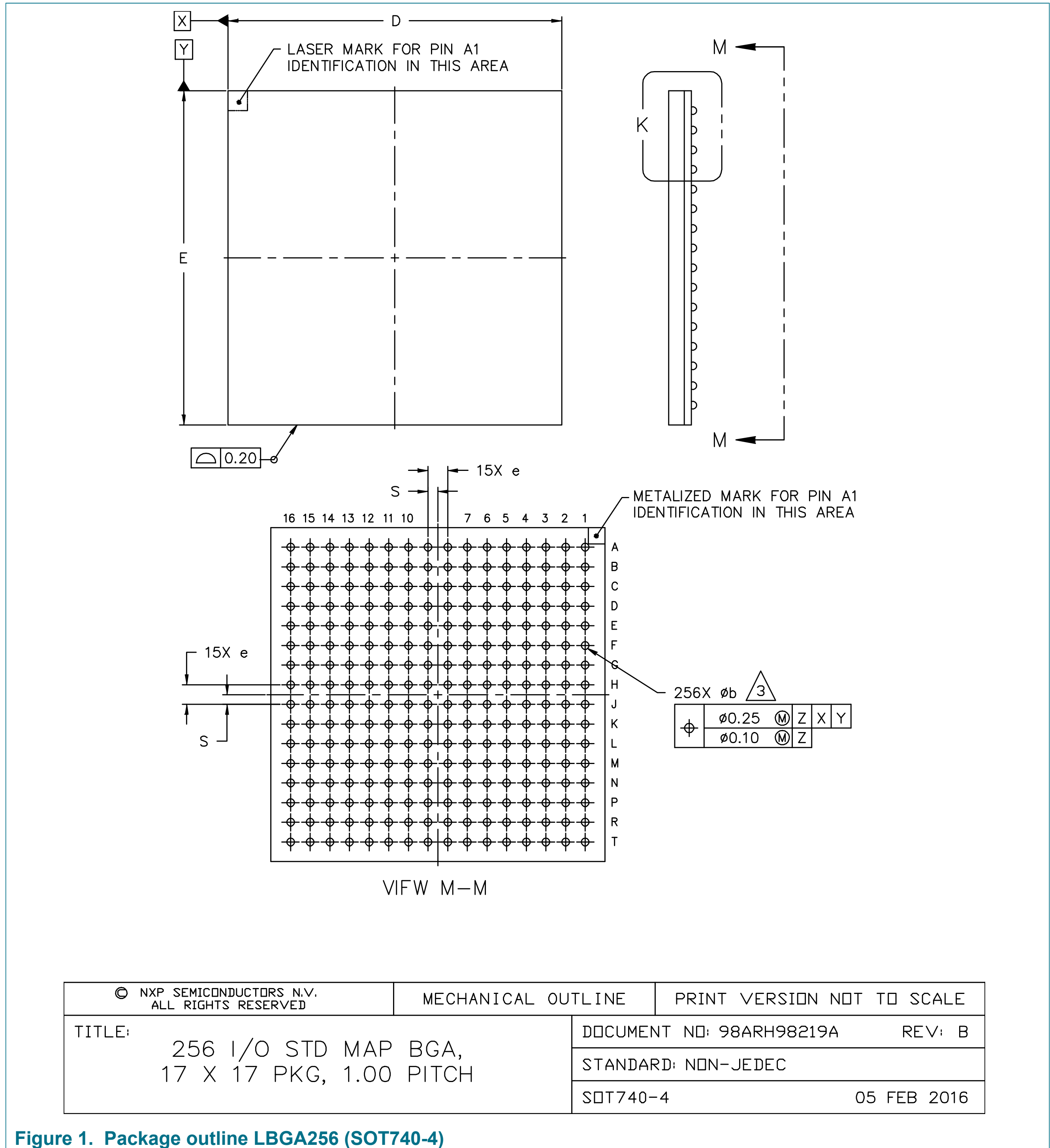

Figure 1. Package outline LBGA256 (SOT740-4)

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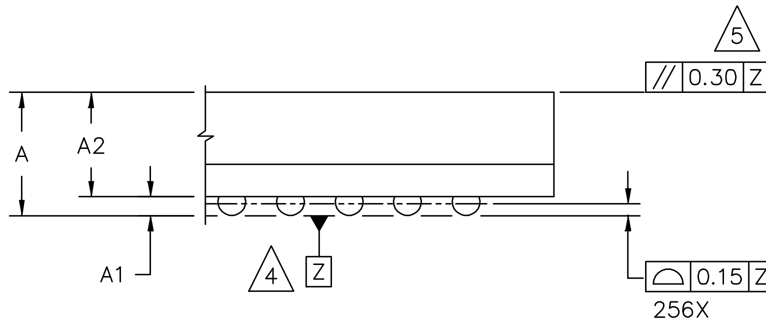

DETAIL K
ROTATED 90° CLOCKWISE

DIM	MIN	MAX	NOTES
A	1.25	1.60	1. DIMENSIONS ARE IN MILLIMETERS.
A1	0.27	0.47	2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M−1994.
A2	1.16 REF		3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z.
b	0.40	0.60	4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
D	17.00 BSC		5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
E	17.00 BSC		
e	1.00 BSC		
S	0.50 BSC		

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TITLE: 256 I/O STD MAP BGA, 17 X 17 PKG, 1.00 PITCH	DOCUMENT NO: 98ARH98219A	REV: B
	STANDARD: NON-JEDEC	
	SOT740-4	05 FEB 2016

Figure 2. Package outline dt1 LBGA256 (SOT740-4)

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3 Legal information

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